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August 2014

## **FQA38N30**

# N-Channel QFET<sup>®</sup> MOSFET 300 V, 38.4 A, 85 m $\Omega$

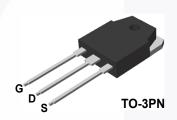
#### **Features**

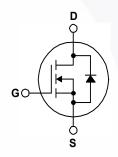
- 38.4 A, 300 V, R<sub>DS(on)</sub> = 85 m $\Omega$  (Max.) @ V<sub>GS</sub> = 10 V, I<sub>D</sub> = 19.2 A
- Low Gate Charge (Typ. 90 nC)
- Low Crss (Typ. 70 pF)
- · 100% Avalanche Tested
- RoHS compliant

### **Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQA38N30	Unit
V <sub>DSS</sub>	Drain-Source Voltage		300	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		38.4	Α
	- Continuous (T <sub>C</sub> = 100°C)		24.3	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	153.6	A
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	1500	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	38.4	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	29	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		290	W
	- Derate above 25°C		2.33	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.43	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA38N30	FQA38N30	TO-3PN	Tube	N/A	N/A	30 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	300			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.35		V/°C
I <sub>DSS</sub>	Zoro Cata Valtaga Drain Current	V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 240 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	-		100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19.2 A		0.065	0.085	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_{D} = 19.2 \text{ A}$		24		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	 3380	4400	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz	 670	870	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		 70	90	pF

#### **Switching Characteristics**

	<u>,                                    </u>		 		
$t_{d(on)}$	Turn-On Delay Time	V <sub>DD</sub> = 150 V, I <sub>D</sub> = 38.4 A,	 80	170	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$	 430	870	ns
$t_{d(off)}$	Turn-Off Delay Time	9	 170	350	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	 190	390	ns
$Q_g$	Total Gate Charge	V <sub>DS</sub> = 240 V, I <sub>D</sub> = 38.4 A,	 90	120	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10 V	 23		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4)	 44		nC

#### **Drain-Source Diode Characteristics and Maximum Ratings**

		•				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				38.4	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				153.6	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 38.4 A			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 38.4 A,		300		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs		2.85		μС

#### Notes

- 1. Repetitive rating : pulse width limited by maximum junction temperature.
- 2. L = 1.7 mH,  $I_{AS}$  = 38.4 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.
- 3.  $I_{SD} \le 38.4$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_J$  = 25°C.
- 4. Essentially independent of operating temperature.

## **Typical Characteristics**

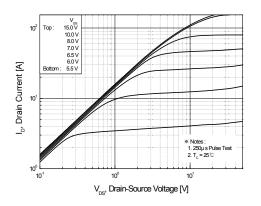
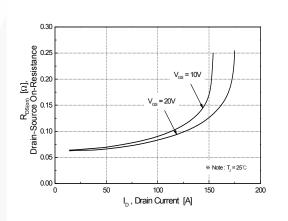


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



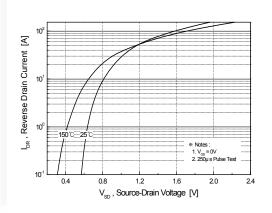
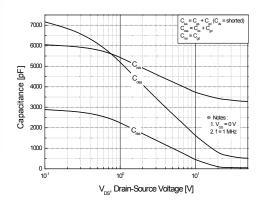


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



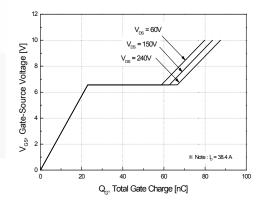
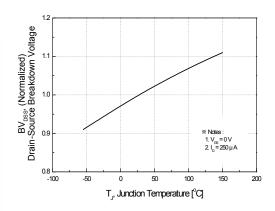


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

## Typical Characteristics (Continued)



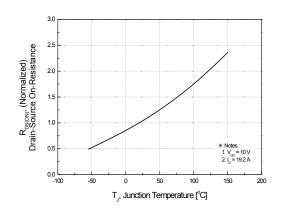
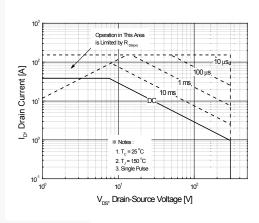


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



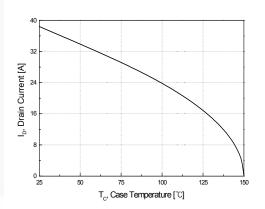


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

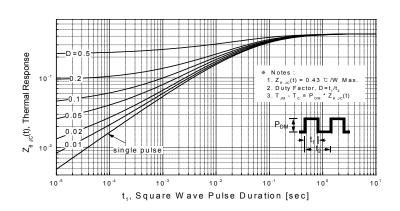


Figure 11. Transient Thermal Response Curve

Figure 12. Gate Charge Test Circuit & Waveform

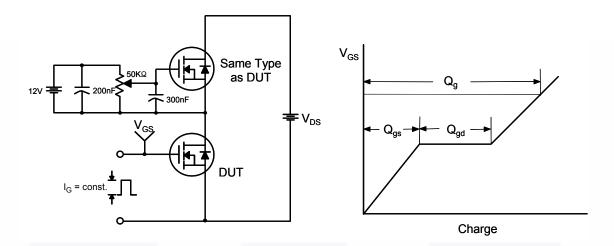


Figure 13. Resistive Switching Test Circuit & Waveforms

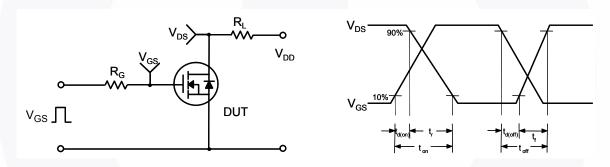
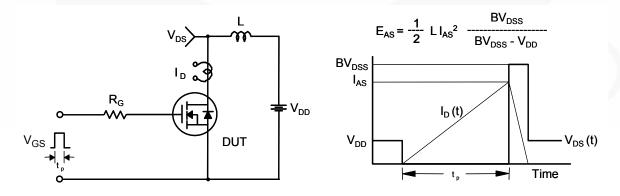
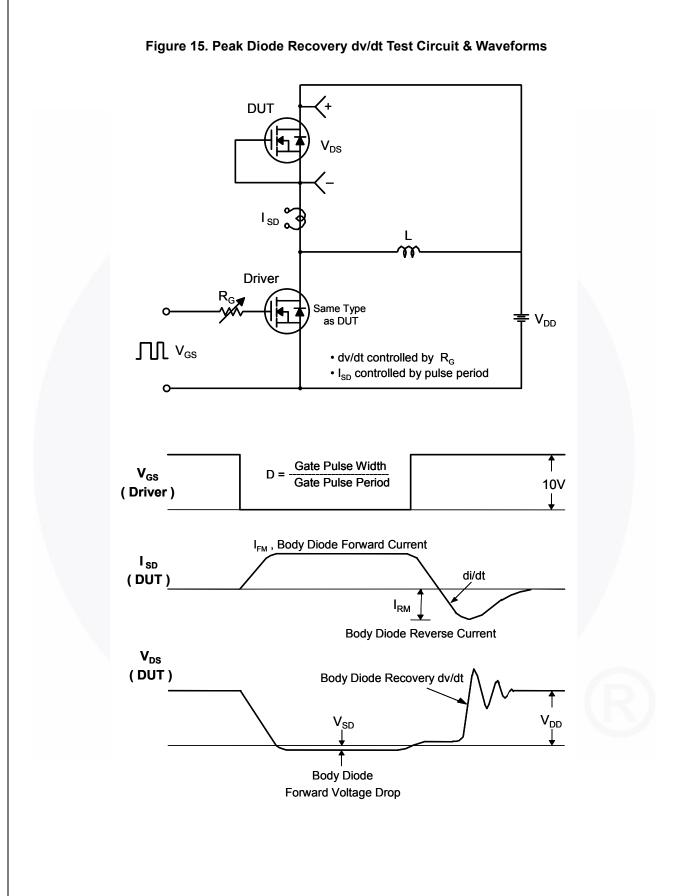
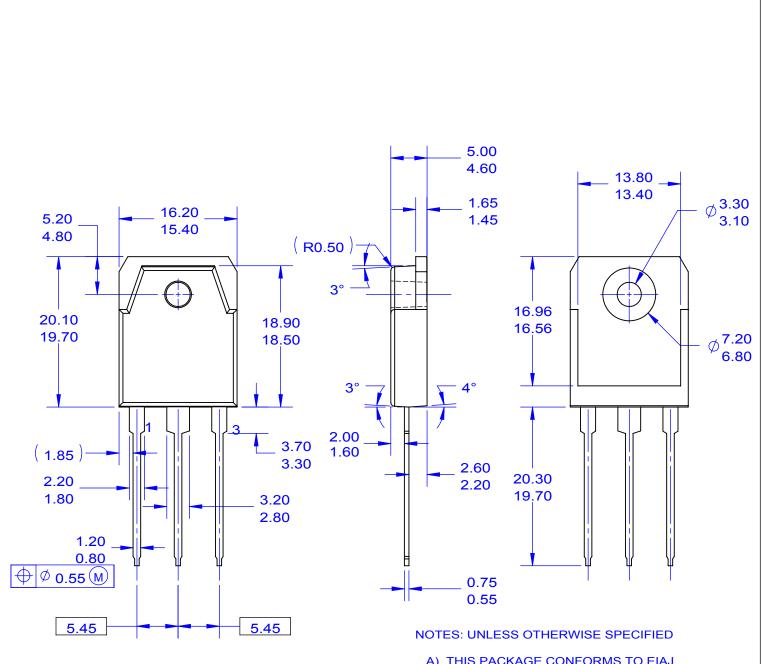
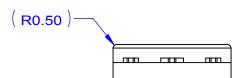


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms









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